

ABSTRACT OF DISCLOSURE

A microelectronic device and methods of fabricating the same comprising a microelectronic die having an active surface, a back surface, and at least one side. The microelectronic die side comprises a beveled sidewall and a channel sidewall. A

- 5 metallization layer is disposed on the microelectronic die back surface and the beveled sidewall.

11/11/91 10:00 AM